

**REPLY UNDER 37 CFR 1.116  
EXPEDITED PROCEDURE  
TECHNOLOGY CENTER 2100**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

<b>Application No.:</b>	10/065,753	<b>Conf. No.:</b>	9185
<b>Applicant:</b>	Chiu et al.	<b>TC/AU:</b>	2128
<b>Filed:</b>	11/15/02	<b>Examiner:</b>	Phan, Thai Q.
<b>Customer No.:</b>	23550	<b>Docket:</b>	BUR920020064 (IBMB-0012)

**Title:** INTEGRATED CIRCUIT AND PACKAGE MODELING

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AFTER FINAL AMENDMENT**

Sir:

**I. INTRODUCTORY COMMENTS:**

In response to the Office Action of January 4, 2006, please amend the above-referenced patent application as follows: